

C1210X682F2TACTU

Aliases (C1210X682F2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 6,800 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	30 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1210	
L	3.3mm +/-0.4mm	
W	2.6mm +/-0.3mm	
Т	0.78mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	

W	2.6mm +/-0.3mm	Tol
Т	0.78mm +/-0.20mm	Vo
S	1.5mm MIN	Die
В	0.6mm +/-0.25mm	Ter
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Packaging Specifications	;	Ca

Specifications	
Capacitance	6,800 pF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	1%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 Applied (TCC)
Packaging Quantity	Packaging Quantity 4000	Dissipation Factor
		Aging Data

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